

# **PRODUCT SPECIFICATION** **FOR LCD MODULE**

**Revision:** 1.0

**Model No:** LS016I03-MP-V1

**Module Type:** COG+FPC+B/L

**APPROVED SIGNATURE**

- Approved Product Specification only
- Approved Product Specification and Samples

<b><u>Prepared By</u></b>	<b><u>Checked By</u></b>	<b><u>Approved By</u></b>

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# 1. General Description

LS016I03-MP-V1 is a transmissive type a-Si TFT-LCD (amorphous silicon thin film transistor liquid crystal display) module, which is composed of a TFT-LCD panel, a driver circuit and a backlight unit. The panel size is 1.6 inch and the resolution is 400(RGB)\*400, the panel can display up to 16M colors.

# 2. Physical Features

Display Mode	TFT-LCD Module
	Active matrix TFT, Transmissive type
Display Format	Graphic 400(RGB)×400 Dot-matrix
Input Data	MIPI input
Viewing Direction (Grayscale Inversion)	Free (IPS)
Drive	ST7797

# 3. Mechanical Specification

Item	Specification	Unit
Module size (H×V×D)	42.14 ×44.23×1.9	mm
Number of dots	400(RGB) ×400	pixel
Active area (H×V)	39.84×39.84	mm



## 5. Absolute Maximum Ratings

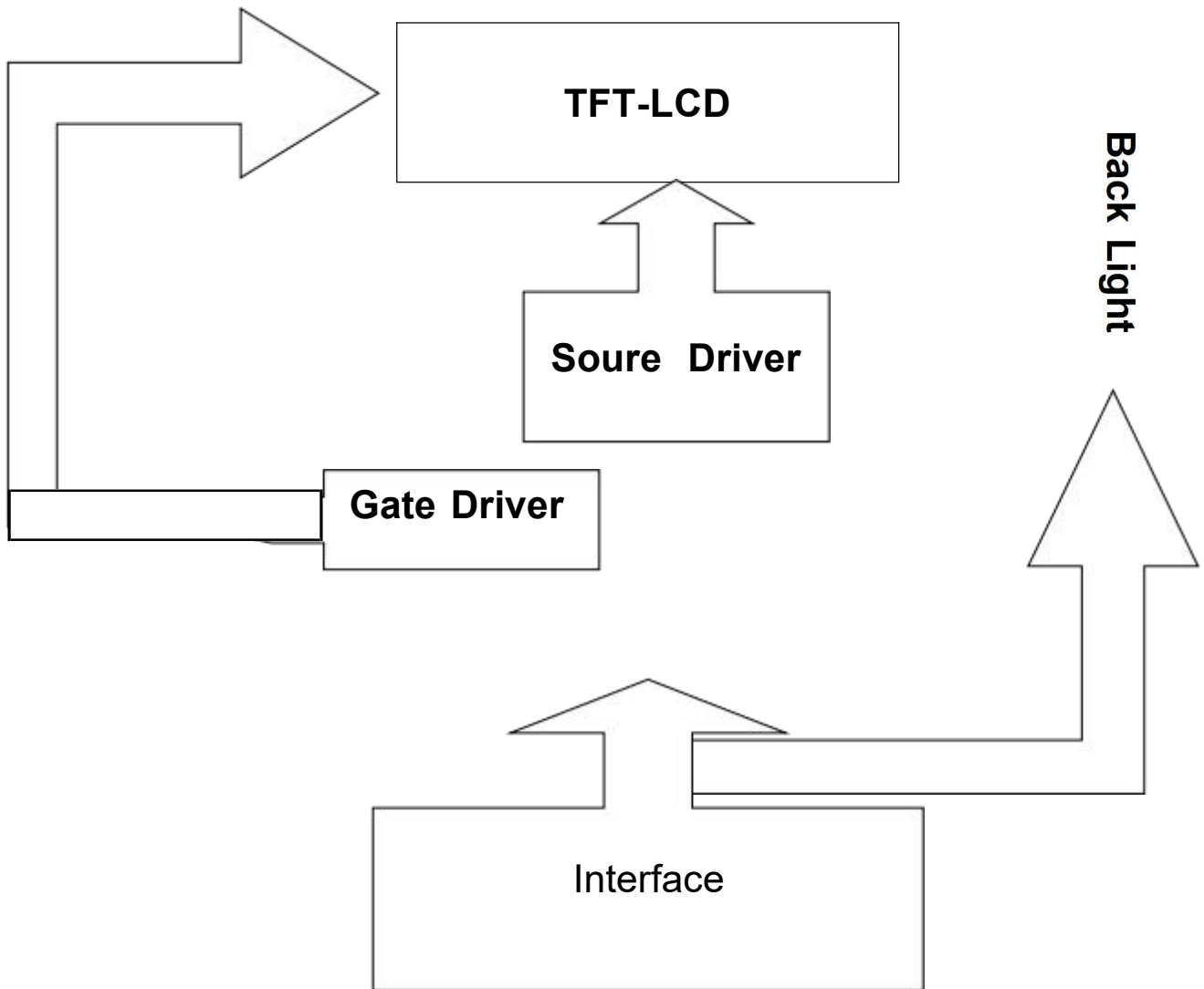
Item	Symbol	Min	Max	Unit	Remark
Supply voltage	VCC	-0.3	4.6	V	Note1 Note2
Supply voltage	IOVCC	-0.3	4.6	V	
Operating temperature	TOPR	-10	70	°C	
Storage temperature	TSTR	-20	80	°C	

## 6. Electrical Characteristics

Item	Symbol	Rating			Unit	Remark	
		Min	Typ	Max			
Supply voltage	VCC	2.6	2.75	3.3	V	Note1	
Supply voltage	IOVCC	1.65	1.8	3.3	V		
Input Voltage	L level	VIL	VSS	---	0.3*IOVCC		V
	H level	VIH	0.7*IOVCC	---	IOVCC		V

## 7. Module Function Description

### 7-1. Block Diagram Of LCM



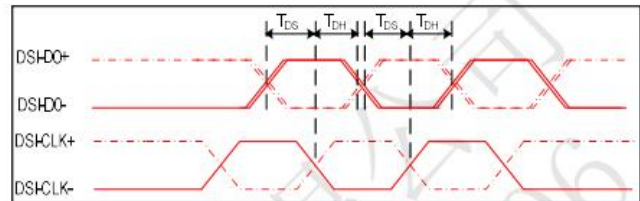
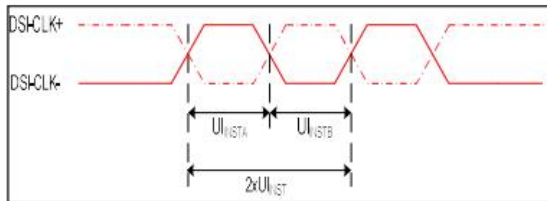
## 7-2. Pin Description

PIN NO.	Symbol	I/O	Description
1	D0N		Negative MIPI differential data inputs
2	D0P		Negative MIPI differential data inputs
3	GND		GND
4	MIPI_CN		Negative MIPI differential clock inputs
5	MIPI_CP		Negative MIPI differential clock inputs
6	GND		GND
7	VDD2.8V		Power voltage
8	IOVCC1.8V		Power voltage
9	RESET		Global reset pin
10	GND		GND
11	LED_K		Power for LED backlight cathode
12	LED_A		Power for LED backlight anode

## 7-3 Timing Characteristics

### 7.3.1. High Speed Mode

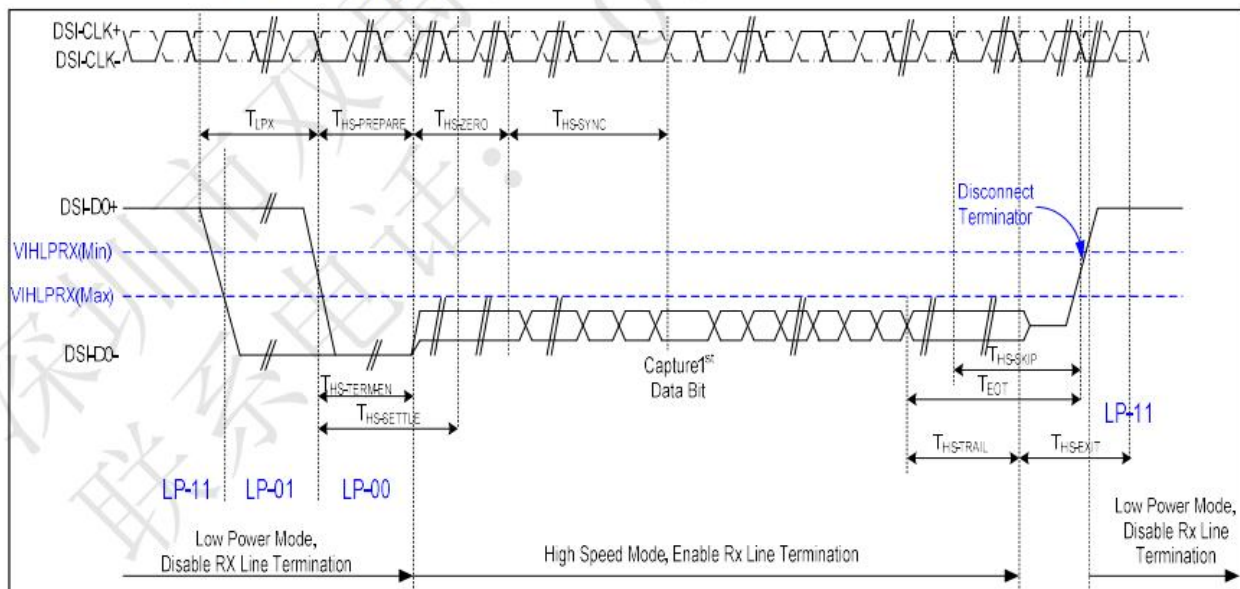
- Clock Channel Timing



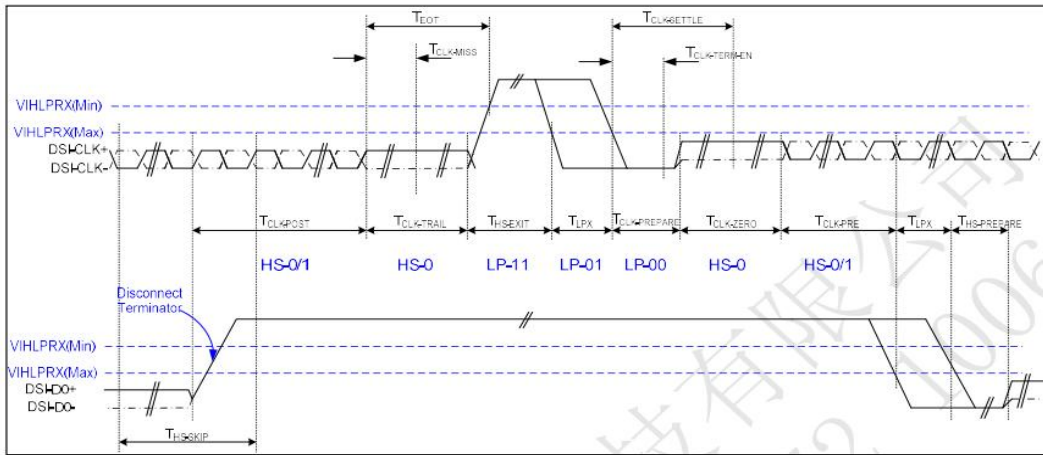
- Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	$2xUI_{INSTA}$	Double UI instantaneous	4	25	ns	-
DSI-CLK+/-	$UI_{INSTA}$ $UI_{INSTB}$	UI instantaneous halves	2	12.5	ns	$UI = UI_{INSTA} = UI_{INSTB}$
DSI-Dn+/-	$t_{DS}$	Data to clock setup time	0.15	-	UI	-
DSI-Dn+/-	$t_{DH}$	Data to clock hold time	0.15	-	UI	-

- Data Transmission



Data lanes-Low Power Mode to/from High Speed Mode Timing

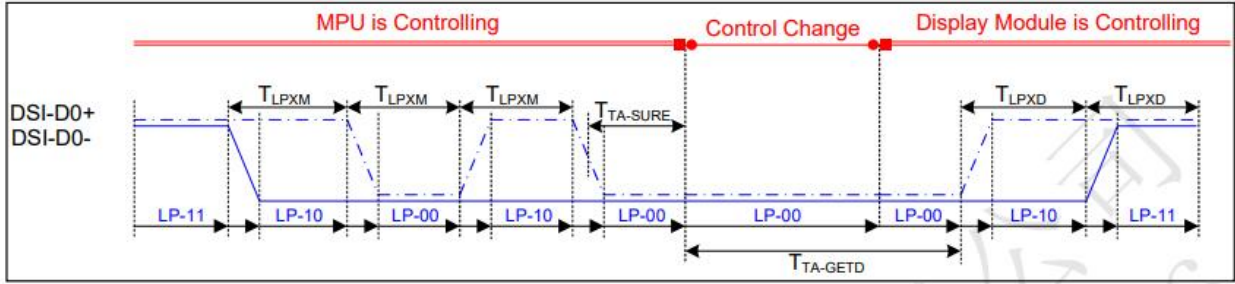


Clock lanes- High Speed Mode to/from Low Power Mode Timing

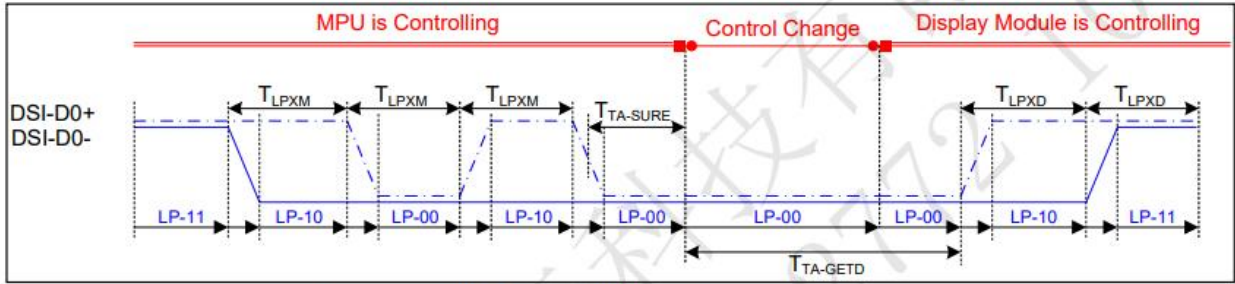
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
Low Power Mode to High Speed Mode Timing						
DSI-Dn+/-	TLPX	Length of any low power state period	50	-	ns	Input
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare for HS transmission	40+4UI	85+6UI	ns	Input
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from when Dn crosses VILMAX	-	35+4UI	ns	Input
DSI-Dn+/-	THS-PREPARE + THS-ZERO	THS-PREPARE + time to drive HS-0 before the sync sequence	140+10UI	-	ns	Input
High Speed Mode to Low Power Mode Timing						
DSI-Dn+/-	THS-SKIP	Time-out at display module to ignore transition period of EoT	40	55+4UI	ns	Input
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-Dn+/-	THS-TRAIL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4UI	-	ns	Input
High Speed Mode to/from Low Power Mode Timing						
DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode	60+52UI	-	ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for HS transmission	38	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time-out at clock lan display module to enable HS transmission	--	38	ns	Input
DSI-CLK+/-	TCLK-PREPARE + TCLK-ZERO	Minimum lead HS-0 drive period before starting clock	300	-	ns	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8UI	-	ns	Input
DSI-CLK+/-	TEOT	Time form start of TCLK-TRAIL period to start of LP-11 state	-	105ns+12UI	ns	Input

Mipi Interface- High Speed Mode Timing Characteristics

### 7.3.2.Low Power Mode



Bus Turnaround (BTA) from display module to MPU Timing



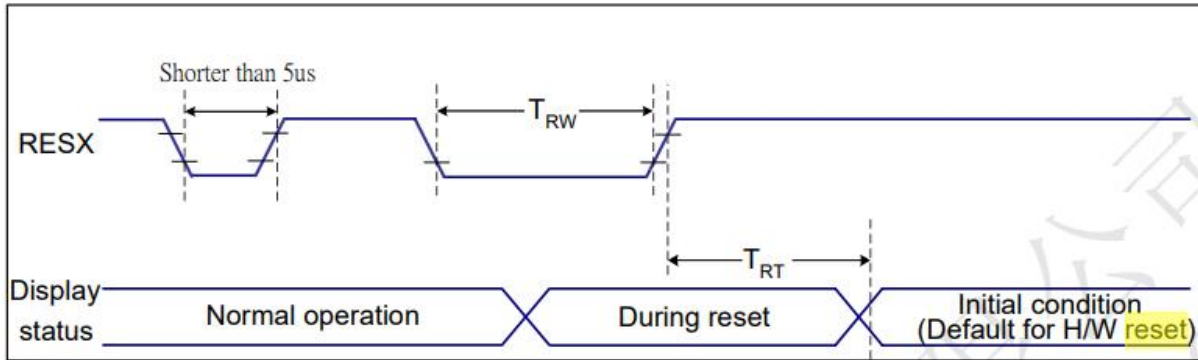
Bus Turnaround (BTA) from MPU to display module Timing

VDDI=1.8V, VCI=2.8V, AGND=DGND=AGNDR=0V, Ta=25°C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-D0+/-	TLPXM	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Input
DSI-D0+/-	TLPXD	Length of LP-00,LP-01, LP-10 or LP-11 periods MPU→Display Module	50	75	ns	Output
DSI-D0+/-	TTA-SURED	Time-out before the MPU start driving	TLPXD	2xTLPXD	ns	Output
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by display module	5xTLPXD		ns	Input
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after turnaround request-MPU	4xTLPXD		ns	Output

MIPI Interface BTA Mode Timing Characteristics

### 7.3.3.Reset Timing

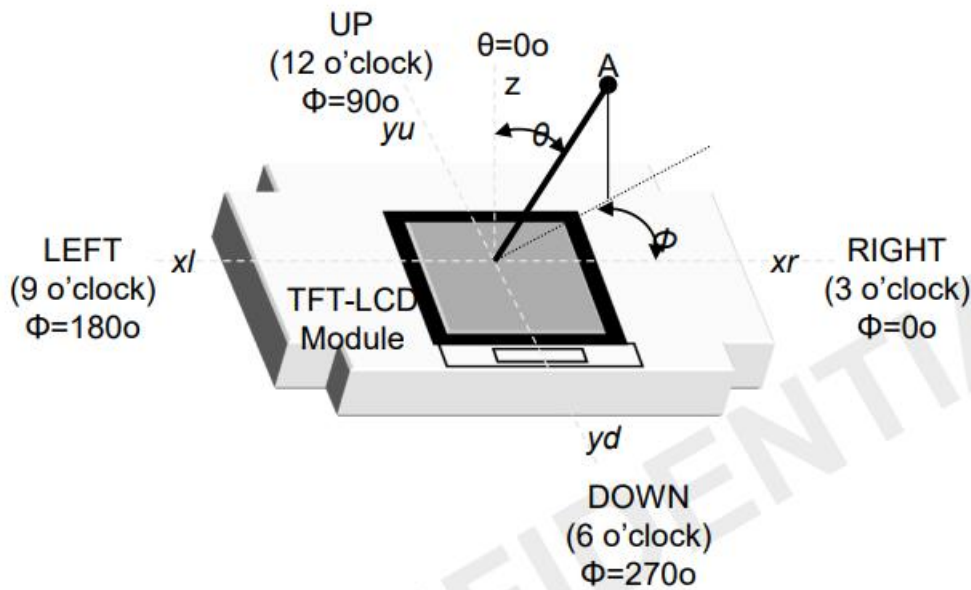


VDDI=1.8V, VCI=2.8V, AGND=DGND=AGNDR=0V, Ta=25 °C

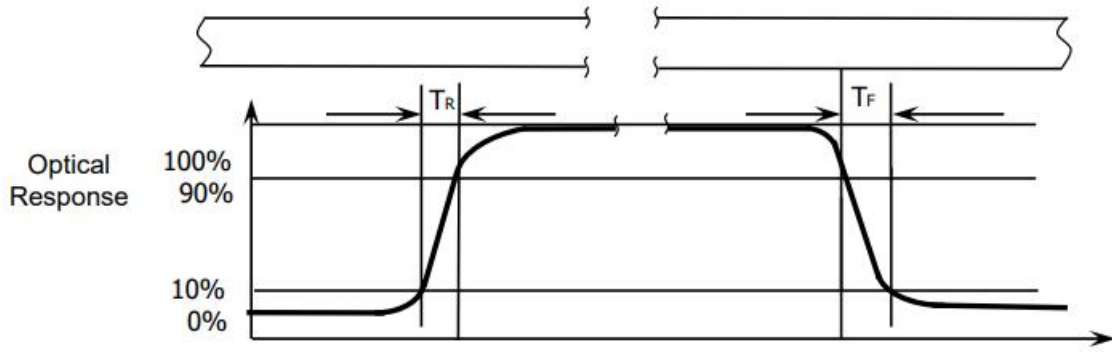
Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
			-	120 (Note 1, 6, 7)	ms

## 8. Electro-Optical Characteristics

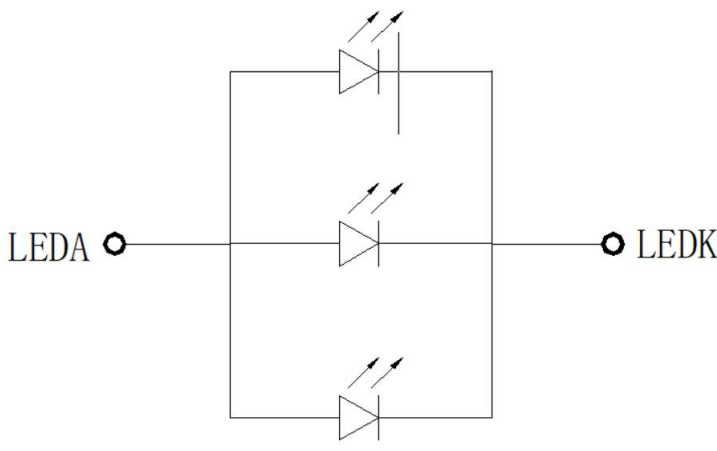
Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark
Response time	Tr +Tf	$\theta_x = \theta_y = 0$	---	25	35	ms	Note 1
Contrast Ratio	CR		900	1200	---	---	Note 2
Transmittance	T%		3.4	4.0	---	%	
Color Chromaticity (CIE1931)	White	W x	---	0.294	---	---	
		W y	---	0.335	---	---	
Viewing angle	$\theta_T$	CR > 10	---	85	---	Deg.	Note 3
	$\theta_B$		---	85	---		
	$\theta_L$		---	85	---		
	$\theta_R$		---	85	---		
Luminance ( $I_F = 60mA$ )	L		400	---	500	cd/m <sup>2</sup>	Note4



$$CR = \frac{\text{Luminance when displaying a white raster}}{\text{Luminance when displaying a black raster}}$$



**Note(4) Backlight circuit**



$I_F=60\text{mA}$       $V_F=2.8\text{V}\sim 3.3\text{V}$

# 9. Inspection Standards

## 1. AQL(Acceptable Quality Level)

AQL of major and minor defect

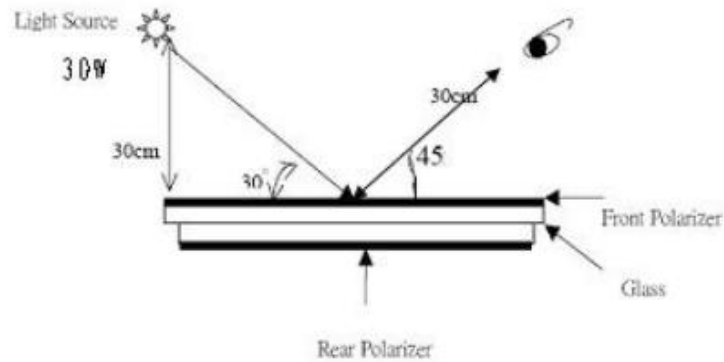
According to GB/T 2828-2003 ; , normal inspection, Class II

MAJOR DEFECT	MINOR DEFECT
0.65	1.5

## 2. Basic conditions for inspection

The LCM face to us, in normal environment, About an angle of incidence 30, a distance of 30cm with normal eye,with an angle of 45 degree to check the products without uncovering the film!

(As shown below)

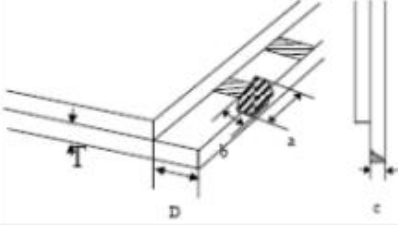
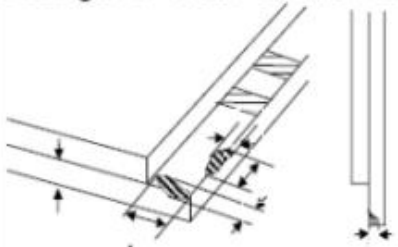


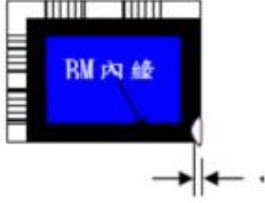
## 3. Inspection item and criteria

### 3.1 Visual inspection criterion in immobility

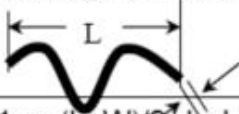
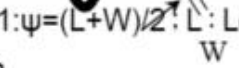
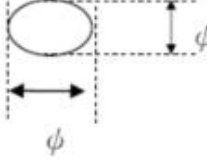
#### 3.1.1 Glass defect

No	Defect item	Criteria	Remark
1	Dimension Unconformity  (Major defect)	By Engineering Drawing	

No	Defect item	Criteria	Remark
2	Cracks  (Major defect)	1.Linear cracks on panel <b>【 Reject 】</b> 2. Nonlinear crack contrast by limited sample	
3	Glass extrude the conductive area  (minor defect)	a: disregards and no influence assemblage 1) $b \leq 1/3$ Pin width(non bonding area) <b>【 Accept 】</b> 2) bonding area $\leq 0.5\text{mm}$ <b>【 Accept 】</b>	a:Length, b:Width
4	Pin-side · conductive area damaged  (minor defect)	(a c : disregards) $b \leq 1/3$ of effective length for bonding electrode  <b>【 Accept 】</b>	a:Length·b:Width·c:Thickness 
5	Pin-side · non-conductive area damaged  (minor defect)	1) Damage area don't touch the ITO (Inclueing contraposition mark,except scribing mark ) <b>【 Accept 】</b> 2) $c < T$ $b \leq BM$ 1/3 of width <b>【 Accept 】</b> 3) $c = T$ b not touch the seal glue <b>【 Accept 】</b> 4) a disregards	a:Length·b:Width·c:Thickness 

No	Defect item	Criteria	Remark
6	Non-pin-side damage  (minor defect)	$c < T$  1) $b$ exceeds $1/3$ BM	$c$ : Thickness $b$ : width of damage  
		$c = T$ $b$ not touch the seal glue  <b>【Reject】</b>  <b>【Reject】</b>	

### 3.1.2 LCD appearance defect (View area)

No	Defect item	Criteria		Remark
1	Fiber · glass crack · polarizer scratch/folded  (minor defect)	Specification	Allowable	note1: $L$ : Length · $W$ : Width note2: disregard if out of AA 
		$0.05\text{mm} < W \leq 0.1\text{mm};$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm}; L > 3.0\text{mm}$	0	
2	Polarizer bubble · concave and convex  (minor defect)	$\psi \leq 0.2\text{mm}$	disregard	note 1: $\psi = (L+W)/2$ ; $L$ : Length · $W$ : Width note2: disregard if out of AA 
		$0.2\text{mm} < \psi \leq 0.3\text{mm}$	2	
		$0.3\text{mm} < \psi \leq 0.5\text{mm}$	1	
		$0.5\text{mm} < \psi$	0	
3	Black dots · dirty dots · impurities · eyewinker  (Major defect)	$\psi \leq 0.15\text{mm}$	disregard	note2: disregard if out of AA 
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
4	Polarizer prick  (Major defect)	$\psi \leq 0.1\text{mm}$	disregard	note1: $\psi = (L+W)/2$ ; $L = \text{Length}$ · $W = \text{Width}$ note2: the distance between two dots $> 5\text{mm}$
		$0.1\text{mm} < \psi \leq 0.25\text{mm}$	3	
		$\psi > 0.25\text{mm}$	0	

### 3.1.3 .FPC

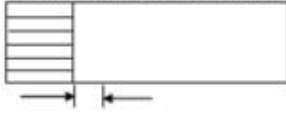
No	Defect item	Criteria		Remark
1	Copper screen peel (Major defect)	Copper screen peel 【 Reject】		
2	No release tape or peel (Major defect)	No release tape or peel 【 Reject】		
3	Dirty dot and impurity of FPC for customer using side (minor defect)	Specification	Allowable	note1: Cannot have stride ITO impurities
		$\psi \leq 0.25\text{mm}$	2	
		$\psi > 0.25$	0	

### 3.1.4 Black tape & Mara tape

1	FPC or H/S black tape shift  (minor defect)	1.shift spec: 1)glue to the polarize 【 Reject】 2) IC bare 【 Reject】 2. left-and-right spec: 1) exceed of FPC edge or H-S edge 【 Reject】 2)IC bare 【 Reject】	
2	No black tape (Major defect)	No black tape 【 Reject】	
3	Tape position mistake (minor defect)	Not by engineering drawing 【 Reject】	
4	Mara tape defect  (minor defect)	Peel before pulling the protecting film. 【 Reject】	

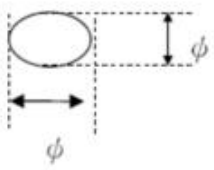
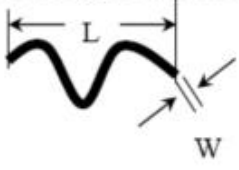
### 3.1.5 Silicon and Tuffy glue

No	Defect item	Criteria	Remark
1	Quantity of silicon (minor defect)	Uncover the ITO and circuit area. 【 Reject】	note: compared by engineering drawing.

No	Defect item	Criteria	Remark
2	Tuffy glue (minor defect)	1. Uncover the reveal copper area <b>【 Reject 】</b> 2. Cover layer 0.3mm(Min) ~ 3.0mm(Max) <b>【 accept 】</b>	note:if customer has special requirement , refer to the technical document. 
3	Depth of glue covering (minor defect)	Depth of glue covering overtop front Polarizer <b>【 Reject 】</b>	Except of the special requirement -

### 3.2 Electrical criteria

No	Defect item	Criteria	Remark
1	No display (Major defect)	No display <b>【 Reject 】</b>	
2	Missing line (Major defect)	Missing line <b>【 Reject 】</b>	
3	Seg-com light and dark (Major defect)	Seg-com light and dark <b>【 Reject 】</b>	ND filter 2% test
4	No display in immobility (Major defect)	No display in immobility <b>【 Reject 】</b>	
5	Flicker of Pattern (Major defect)	Flicker of Pattern <b>【 Reject 】</b>	
6	Mura (Major defect)	ND filter 2% test	
7	Over current (Major defect)	Over current <b>【 Reject 】</b>	
8	Voltage out of specification (Major defect)	Voltage out of specification <b>【 Reject 】</b>	
9	Pattern blur ,error code (Major defect)	Pattern blur ,error code <b>【 Reject 】</b>	
10	Dark light, Flicker (Major defect)	Dark light, Flicker <b>【 Reject 】</b>	

No	Defect item	Criteria	Allowable	Remark
11	Black/White dots · Dirty dots · eyewinker  (Major defect)	Specification	Allowable	Note1: disregard if out of AA  
		$\psi \leq 0.15\text{mm}$	disregard	
		$0.15\text{mm} < \psi \leq 0.25\text{mm}$	2	
		$0.25\text{mm} < \psi \leq 0.3\text{mm}$	1	
		$0.3\text{mm} < \psi$	0	
12	Fiber · glass cratch · polarizer scratch/folded  (minor defect)	$W \leq 0.03\text{mm}$	disregard	note1: L : Length · W : Width note2: disregard if out of AA  
		$0.03\text{mm} < W \leq 0.05\text{mm} ;$ $L \leq 3.0\text{mm}$	2	
		$0.05\text{mm} < W \leq 0.1\text{mm} ;$ $L \leq 3.0\text{mm}$	1	
		$W > 0.1\text{mm} ; L > 3.0\text{mm}$	0	

